- 14. A system comprising:
- a first circuit assembly comprising a first surface connected to a first component, a second component, and a bracket surrounding the first component; and
- a second circuit assembly comprising a second surface connected to a spacer disposed between the second component and the second surface.
- 15. The system of claim 14, wherein the spacer is configured to contact the second component when the second surface is bent toward the first surface.
- **16**. The system of claim **14**, wherein the spacer includes a curved convex profile relative to the second surface.
- 17. The system of claim 14, wherein a first thickness of the bracket is greater than a second thickness of the first component.
- 18. The system of claim 14, wherein the first component and the second component are connected to different sides of the first surface.
- 19. The system of claim 14, wherein the second component is a processor that is thicker than the spacer.
- 20. The system of claim 14, wherein at least one of the bracket and the spacer is made from a metal alloy.

\* \* \* \* \*